

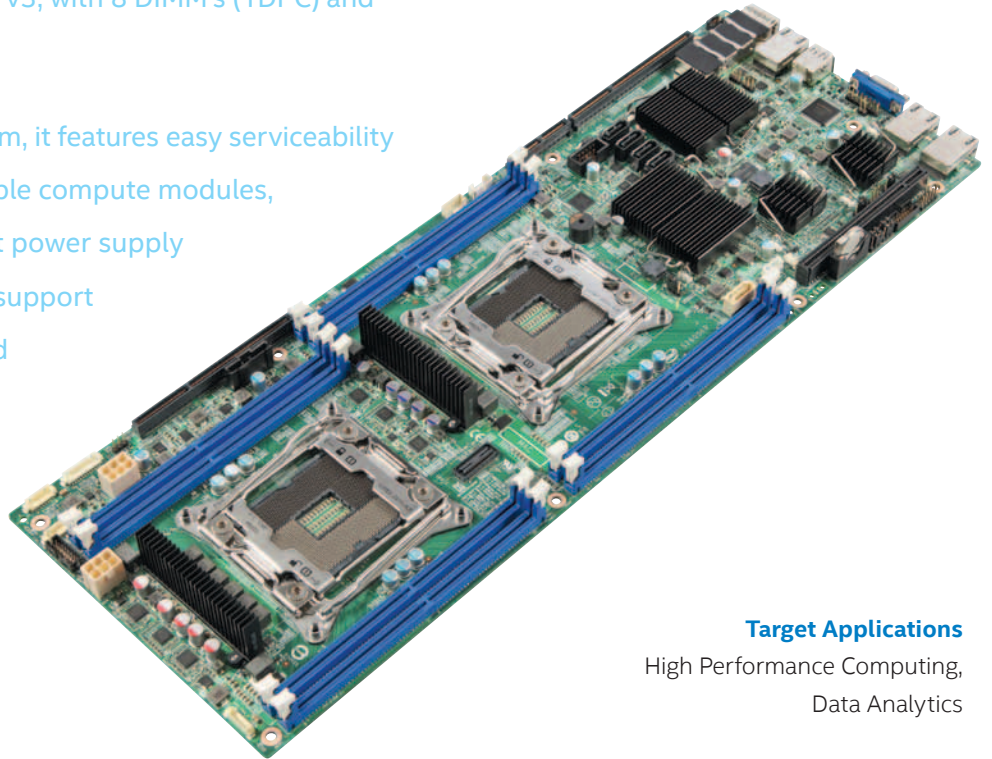
Intel® Server Board S2600KP Product Family

Efficient, high-density solution with optimized memory performance for preferred value in high performance computing (HPC) deployments



The Intel® Server Board S2600KP is specifically designed for optimal memory performance in the HPC market. It features support for dual Intel® Xeon® processors E5-2600 v3, with 8 DIMM's (1DPC) and optional onboard FDR Infiniband*.

Customizable as a 2U, four node system, it features easy serviceability and high availability with hot-swappable compute modules, 2.5" or 3.5" drive bays, and redundant power supply modules plus better I/O flexibility via support for Intel® I/O Modules, and an onboard dedicated management port.



Target Applications

High Performance Computing,
Data Analytics

INTEL® SERVER BOARD S2600KP PRODUCT FAMILY

FEATURES

Dual Intel® Xeon® processor E5-2600 v3 product family, 145W max TDP, 160 W for board only

Maximum TDP processor support for 3rd party solutions with custom water cooling design

8 DDR4 DIMM slots (1DPC), up to 128GB per DIMM, 1.0 TB total memory

3 risers, 64 I/O lanes available on the board, Connect IB FDR Infiniband* onboard option

BENEFITS

Fits up to 4 boards (8 sockets) in a 2U rack chassis for highly demanding distributed processing and intensive application workloads

Enables efficient computing performance

Memory bandwidth and capacity optimized for performance

High I/O capacity in a dense form factor board

Technical Information

Description	A high density, half width form factor with dual Intel® Xeon® processors E5-2600 v3 support and 8 DIMMs per server board designed for efficient HPC environments
Form Factor	Board: custom (6.4" x 17.7") 2U rack: 3.5" drive model (17.24" x 30.35" x 3.42") 2.5" drive model (17.24" x 28.86" x 3.42")
Compute Node Supported Each chassis will support up to 4 nodes	HNS2600KP: 8 DIMM Slots HNS2600KPF: 8 DIMM Slots, InfiniBand* FDR (56-Gb/s)
Processors Supported	Dual Intel® Xeon® processor E5-2600 v3 product family
Total Slots	3 riser slots
Slot Types	PCI Express * x24 riser super slot, and PCI Express 3.0 x16 riser slot
Memory Capacity	4 x 8 DIMM slots supporting ECC DDR4 RDIMM and LRDIMM with 1333MT/s, 1600MT/s, 1866MT/s, and 2133MT/s speeds 1 TB max
Drive Options	16 x 2.5" or 12 x 3.5" hot-swap drives
System Cooling	Fixed cooling fans
Power Supply Options	1600W common redundant power supply (Platinum Efficiency)

Available SKUs

Intel® Server Boards S2600KP Family	Intel® Compute Modules HNS2600KP Family	Intel® Server Chassis H2000G Family
S2600KPF (w/ Infiniband)	HNS2600KPF (w/ Infiniband)	H2312XXKR2
S2600KP	HNS2600KP	H2216XXKR2



For more information on Intel server solutions visit: intelservedge.com
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For product specifications visit: ark.intel.com

Product does not include memory, processors, or hard drives. For compatibility information please refer to the configuration guide at www.intel.com/support

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